


Full Material Declaration for attached parts list

Report generated: 01 October 2024, 07:12 GMT

	<p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany Declarations authorised by Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 02 January 2014 [Approved: 01 October 2024 07:05 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	0.46%	Silicon	7440-21-3	100%
			Oxirane, [[4-(1,1-dimethylethyl)phenoxy]methyl]-	3101-60-8	1%
Die attach	Other nonferrous metals	0.91%	Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5	15%
			SILVER, ELEMENTAL	7440-22-4	84%
			Aluminum oxide trihydrate	21645-51-2	0.1%
			Carbon black	1333-86-4	0.5%
			resin	9003-35-4	5%
Encapsulation	EP (Epoxy resin)	48.91%	Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	10%
			Quartz silica	14808-60-7	84.4%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.04%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	5.5%	Tin	7440-31-5	100%
			Phosphorus	7723-14-0	0.03%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	44.18%	IRON, ELEMENTAL	7439-89-6	0.27%
			SILVER, ELEMENTAL	7440-22-4	2.7%
			COPPER, ELEMENTAL	7440-50-8	97%

Attached parts list

Part number	Part name
SOT-26/SOT-457-HF	Diode / Transistor SMD